

CLAIMS

1. An Internet automatic electrical data system,
comprising :

5 a process controller used to process the analyzing
order for IC packages entrusted by clients ;

a working database coupled to said process
controller, used to store the IC package parameters input
by said a client ;

10 a condition parameter database coupled to said
process controller to provide the condition parameters
relative to the model of the IC package entrusted by said
clients ;

15 an electrical simulation and analyzing software
used to analyze said IC package parameters input by said
clients and said condition parameters provided by said
condition parameter database ;

20 a report form generator coupled to said electrical
simulation and analyzing software to generate the report
form of analyzing result ; and

replying means coupled to said report form
generator to send said report forms to said clients.

25 2. A system of claim 1, wherein said client transmits
said IC package parameters through Internet.

30 3. A system of claim 1, wherein said replying means
sends said report forms to said clients comprises the
usage of the electronic mail and facsimile.

4. A system of claim 1, wherein said process
controller accesses said condition parameters from said
condition parameter database, and then transfers said

condition parameters along with said IC package parameters input by said clients to said electrical simulation and analyzing software.

5 5.A system of claim 1, wherein the IC package types provided by said condition parameter database comprise BGA (ball grid array) , BCC, QFP, SOP, QFN(quad flat no-lead), Flip Chip, CSP (chip scale package) , and WLCSP (wafer level chip scale package) .

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6.A system of claim 1, wherein said IC package parameters input by said clients comprises the number of I/O (input and output) terminals, package type, substrate layer, substrate thickness, information about
15 lead frame, and frequency.

7.A system of claim 1, wherein said electrical simulation and analyzing software constructs a three-dimensional model according to said IC package parameters and said condition parameters.
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8.A system of claim 7, wherein said electrical simulation and analyzing software calculates the resistance, inductance and capacitance of said IC package according to said IC package parameters and said condition parameters.
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9.A system of claim 1, wherein said electrical simulation and analyzing software transfers said analyzing result to said report form generator.
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10.A method for automatic analyzing electrical data through Internet, which comprises following steps :

inputting IC package parameters for analyzing by a

client ;

transferring said IC package parameters to a working database for storing through Internet ;

5 accessing said IC package parameters from said working database and condition parameters relative to said IC package parameters from a condition parameter database by a process controller ;

10 transferring said IC package parameters and said condition parameters to an electrical simulation and analyzing software for simulating and analyzing by said process controller ;

transferring the analyzing result to a report form generator for generating the report form of analyzing result ;

15 said report form generator transferring said report form to replying means ; and

sending said report form to said clients by said replying means.

20 11.A method of claim 10, wherein said client transmits said IC package parameters through Internet.

12.A method of claim 10, wherein said client transmits said IC package parameters through Internet.

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13.A method of claim 10, wherein said IC package parameters input by said client comprises the number of I/O terminals, package type, the number of the substrate layer, substrate thickness, information about lead frame, and frequency.

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14.A method of claim 10, wherein said electrical simulation and analyzing software constructs a three-

dimensional model according to said IC package parameters and said condition parameters.

5 15.A method of claim 14, wherein said electrical simulation and analyzing software calculates the resistance, inductance, and capacitance of said IC package according to said IC package parameters and said condition parameters.

10 16.A method of claim 10, wherein the IC package types provided by said condition parameter database comprise BGA (ball grid array) , BCC, QFP, SOP, QFN(quad flat no-lead), Flip Chip, CSP(chip scale package), and WLCSP (wafer level chip scale package) .